Semiconductor Device Type:	R8X	LQFP-48-7x7x1.4mm-MatteTin			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon	7440-21-3	Die	6.12	8.79	61243
Copper	7440-50-8	Leadframe	34.29	49.21	342945
Iron	7439-89-6	Leadframe	0.83	1.19	8266
Zinc	7440-66-6	Leadframe	0.04	0.06	422
Metallic Phosphorus	7723-14-0	Leadframe	0.01	0.02	106
Silver	7440-22-4	Leadframe Plating	0.85	1.22	8468
Formaldehyde, oligomeric reaction products with 1-chloro-2,3-epoxypropane andphenol	9003-36-5	Die Attach	0.07	0.10	692
1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	Die Attach	0.01	0.01	65
Formaldehyde, oligomeric reaction products with phenol	9003-35-4	Die Attach	0.01	0.01	65
2-butoxyethyl acetate	112-07-2	Die Attach	0.02	0.02	173
Silver	7440-22-4	Die Attach	0.33	0.48	3332
Gold	7440-57-5	Bonding Wire	0.60	0.85	5959
Others	Trade Secret	Bonding Wire	0.01	0.01	60
Epoxy Resin A	Trade Secret	Molding Compound	0.55	0.79	5523
Epoxy Resin B	Trade Secret	Molding Compound	0.55	0.79	5523
Phenol Resin	Trade Secret	Molding Compound	2.76	3.96	27614
Silica(Amorphous) A	60676-86-0	Molding Compound	45.29	64.98	452869
Silica(Amorphous) B	7631-86-9	Molding Compound	5.52	7.92	55228
Carbon Black	1333-86-4	Molding Compound	0.55	0.79	5523
Tin	7440-31-5	Lead Finish Plating	1.59	2.28	15925
		TOTALS:	**100.00**	**143.48**	**1,000,000**

143.48 mg Total Mass

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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Package Homogeneous Materials

8.79	**(mg) Total**	**Die**	**% of Total Weight**	**6.12**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
50.47	**(mg) Total**	**Leadframe**	**% of Total Weight**	**35.17**
	Copper	7440-50-8	97.50	
	Iron	7439-89-6	2.35	
	Zinc	7440-66-6	0.12	
	Metallic Phosphorus	7723-14-0	0.03	
		Total	**100.00**	
1.22	**(mg) Total**	**Leadframe Plating**	**% of Total Weight**	**0.85**
	Silver	7440-22-4	100.00	
		Total	**100.00**	
0.62	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.43**
	Formaldehyde, oligomeric reaction products with 1-chloro-2,3-epoxypropane andphenol	9003-36-5	16.00	
	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	1.50	
	Formaldehyde, oligomeric reaction products with phenol	9003-35-4	1.50	
	2-butoxyethyl acetate	112-07-2	4.00	
	Silver	7440-22-4	77.00	
		Total	**100.00**	
0.86	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**0.60**
	Gold	7440-57-5	99.00	
	Others	Trade Secret	1.00	
		Total	**100.00**	
79.24	**(mg) Total**	**Molding Compound**	**% of Total Weight**	**55.23**
	Epoxy Resin A	Trade Secret	1.00	
	Epoxy Resin B	Trade Secret	1.00	
	Phenol Resin	Trade Secret	5.00	
	Silica(Amorphous) A	60676-86-0	82.00	
	Silica(Amorphous) B	7631-86-9	10.00	
	Carbon Black	1333-86-4	1.00	
		Total	**100.00**	
2.28	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**1.59**
	Tin	7440-31-5	100.00	
143.48		**Total**	**100.00**	100.00